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OCP-IP Provides Virtual Platform Leveraging Advanced OCP SystemC TLM Modeling Kit

Beaverton, OR., — August 23, 2010 — Open Core Protocol International Partnership (OCP-IP), the organization delivering a common standard for intellectual property core interfaces that facilitate "plug and play" SoC design, and CircuitSutra, experts in SystemC modeling and embedded software development, along with Imperas, the company providing the infrastructure for the future of software virtual platforms and enabling the next generation of embedded software development, today announced the availability of a Virtual Platform Demo created utilizing OCP-IP's advanced Modeling Kit. This example platform acts as a guide to OCP-IP members enabling them to quick-

start their ESL activities using the OCP-IP TLM Modeling Kit; which is fully compatible with OSCI's TLM 2.0.1. Both the kit and Virtual Platform examples are free to both OCP-IP members and non-members.

The Virtual Platform Demo utilizes [Open Virtual Platforms \(OVP\)](#) technology. OVP was founded by [Imperas](#) to make virtual platforms more accessible and easier to use for embedded software development. OVP includes the OVPsim simulator, model libraries (including nearly 50 different processor core models) and modeling APIs which enable users to easily create their own processor, peripheral and platform models. All OVP processor models include a SystemC/TLM-2.0 interface for easy integration in those virtual platform environments. OVPsim is free for evaluation and non-commercial usage, including OCP-IP members using the Virtual Platform Demo.

Using the kit, CircuitSutra built a comprehensive virtual platform that boots the busybox embedded Linux operating system in about 10 seconds, and can be used for embedded software development. Features like run time bindability, memory management etc. provided in the OCP Modeling Kit are used in the platform.

Peripheral models support TL4 and TL3 abstraction levels and models can be further refined for lower abstraction levels (TL2, TL1), supported by other powerful features of the OCP-IP TLM Kit such as timing information distribution, non default timing, OCP

specific payload extensions and phases, etc.

The example platform makes heavy use of the OCP-IP Modeling Kit which was developed by OCP-IP member companies working in collaboration with [Greensocs, Ltd.](#) It interoperates seamlessly with other TLM utilities, such as GreenSocket from GreenSocs and the methodology used is equally applicable to other buses and platforms, providing, and proving a TLM-2.0 based commonality of approach.

“The OCP Modeling Kit is the most advanced TLM-2.0 based, industry-ready kit in existence today, and this virtual platform allows our members to jump-start their ESL activities using the Kit, said Ian Mackintosh, President and Chairman of OCP-IP. “ This Virtual Platform Demo further extends the high level support and tools OCP-IP provides to members, and highlights the productive cooperation we routinely achieve between companies and industry organizations.”

OCP-IP members can access both the OCP Modeling Kit and the Virtual Platform Demo at www.ocpip.org. Non-members may also access free copies of the OCP modeling kit (without monitors) at the same address.

For more information on OCP-IP's Modeling Kit, please see http://www.ocpip.org/uploads/documents/OCP_TLM_Datasheet.new.pdf.

For the latest information on OCP-IP please see our newsletter at <http://www.ocpip.org/newsletters.php>

About CircuitSutra

CircuitSutra is an emerging company based in India, with a goal to become the **world leader in software services to the semiconductor industry**. Founded in November 2005, CircuitSutra is established as a centre of excellence in **SystemC based SoC Modeling**. CircuitSutra has an in-depth understanding of various standards in modelling domain (OSCI TLM2.0, OCP-IP TLM Kit, STARC TL Guidelines, GreenSocs) and also provides embedded software services using virtual platforms. They are the first company in India to receive seed funding from JSSATE, Science & Technology Entrepreneurs Park (STEP) and are the recipient of ISBA Entrepreneurship Award, 2008. For more information, see www.circuitsutra.com

About Imperas

Imperas provides methodologies, technologies and products to enable the efficient and effective verification of software functionality and software performance for embedded systems. Its products enable software functional verification, performance profiling, analysis and debug for embedded software operating on multicore SoCs and multiprocessor systems. Imperas virtual platform simulators execute platforms, including multicore platforms, at hundreds of million instructions per second,

providing the speed that software developers require for simulation of embedded systems. For more information, visit www.imperas.com.

About OCP-IP

Formed in 2001, OCP-IP is a non-profit corporation promoting, supporting and delivering the only openly licensed, **core-centric protocol** comprehensively fulfilling integration requirements of **heterogeneous multicore** systems. The Open Core Protocol (OCP) facilitates IP **core reusability** and reduces design time, risk, and manufacturing costs for all SoC and **electronic designs** by providing a comprehensive supporting infrastructure. For additional background and membership information, visit www.OCP-IP.org.

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